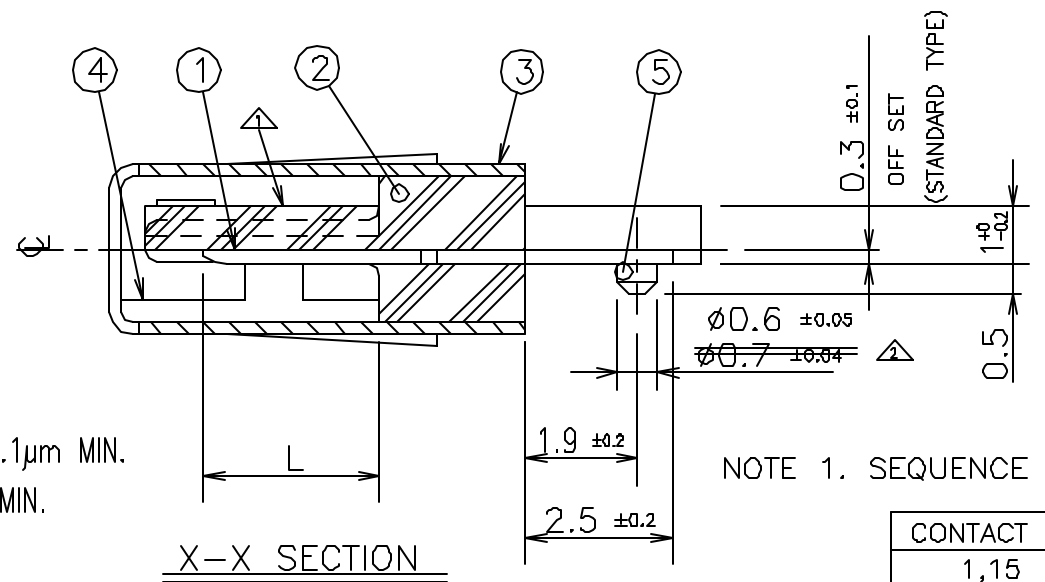
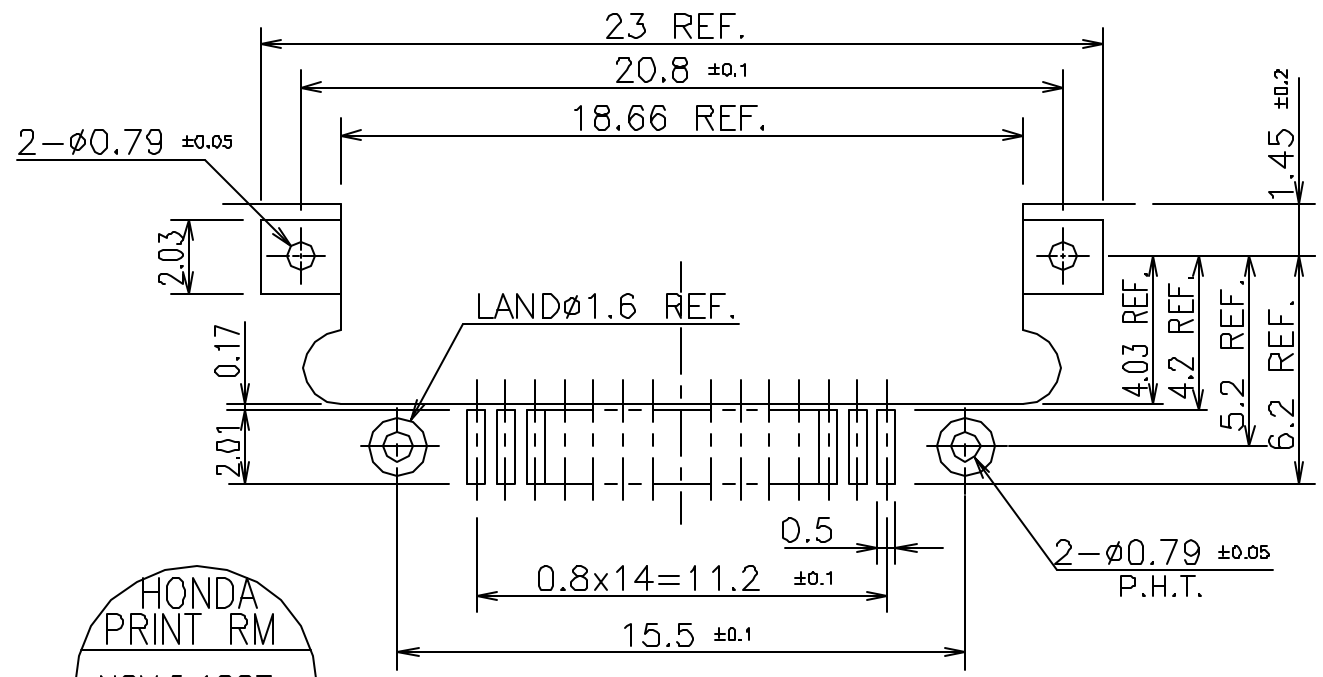
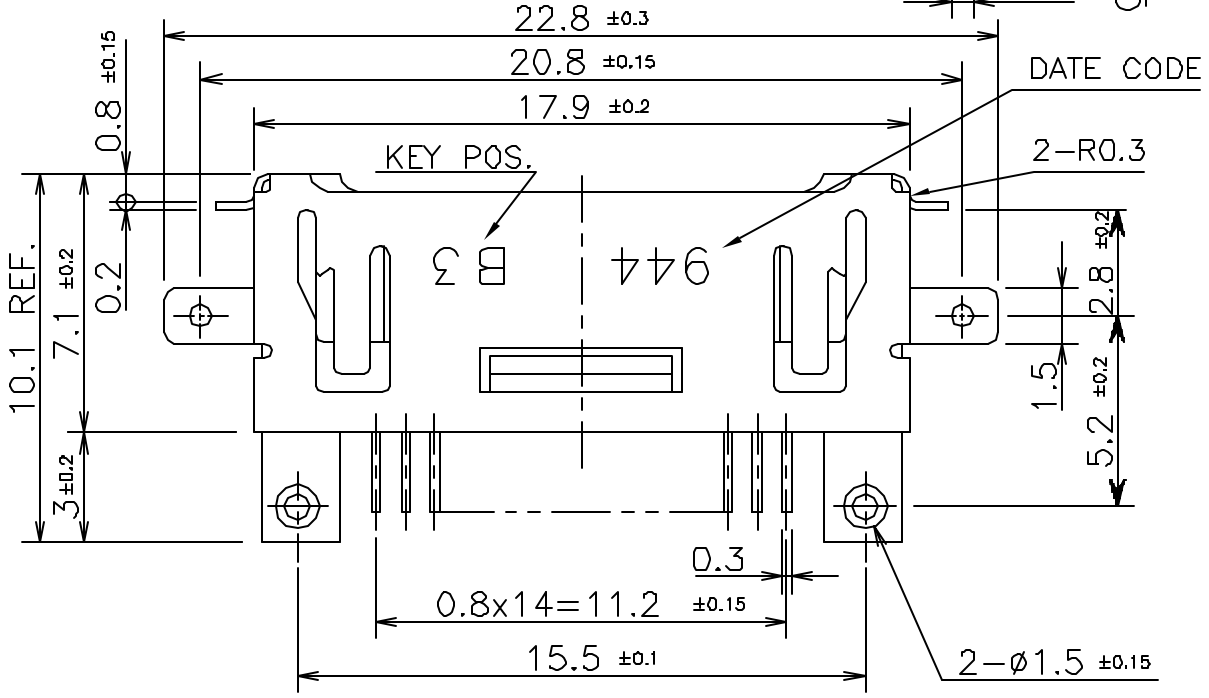
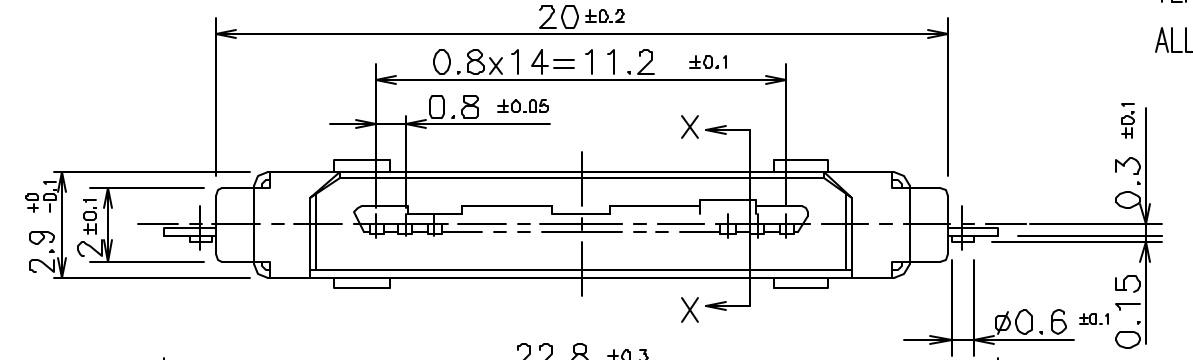


NOTE 2. CONTACT PLATING  
 CONTACT AREA:GOLD 0.1μm MIN.  
 OVER Pd/Ni(9:1)1μm MIN.  
 TERMINAL AREA:TIN.  
 ALL OVER:Ni 1.27μmMIN.



NOTE 1. SEQUENCE CONNECTION

CONTACT POS.	L
1,15	3.9
OTHERS	3.0



HONDA  
 PRINT RM  
 NOV.5.1997  
 ISSUED

PART No.	POLARIZATION KEY	MARKING	APPLICABLE FEMALE CONNECTOR
RMC-E15MY-OM-MB1		1	B1 RMC-E15FB-BSL( )-MB23
RMC-E15MY-OM-MB2		2	B2 RMC-E15FB-BSL( )-MB13
RMC-E15MY-OM-MB3		3	B3 RMC-E15FB-BSL( )-MB12

NO.	PART NAME	MATERIAL	QTY	FINISH	NOTE
5	HOLD DOWN	COPPER ALLOY	2	NICKEL + TIN PLATING	---
4	LOCK PLATE	STAINLESS STEEL	2	---	---
3	SHELL	STAINLESS STEEL	1	NICKEL PLATING	---
2	INSULATOR	PPS(GF)	1	---	UL94V-0 BROWN
1	MALE CONTACT	COPPER ALLOY	15	SEE NOTE2	---

DATE	SCALE	UNIT	3RD . A . P	HONDA TSUSHIN KOGYO., LTD.	
APR.28 1994	5 / 1	mm(INCH)	REV.1B	DR	IE
				CHK	CHK
				APP	NAME
				REAR OF MEMORY CARD SHIELDED I/O MALE 15 POS. CONNECTOR, OFF SET TAIL (0.3)	
				PART NO. RMC-E15MY-OM-MB( )	

RMC-E15MY-5003